



APPROVAL SHEET

| Approval Specification | Customer's Approval Certificate |
|--|---|
| <p>TO:</p> <p>Part No.:</p> <p>Customer's Part No.:</p> | <p>Please return this copy as a certification of your approval</p> <p>Checked & Approved by:</p> <p>Date:</p> |

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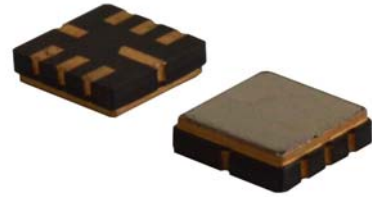


| | | |
|----------|---|-----------|
| Part No. | : | SF1258 |
| Pages | : | 6 |
| Date | : | 2013/3/25 |
| Revision | : | 1.1 |

| | |
|---------------------|-----|
| Prepared by: | 郑宝琴 |
| Checked by: | |
| Approved by: | |

Application

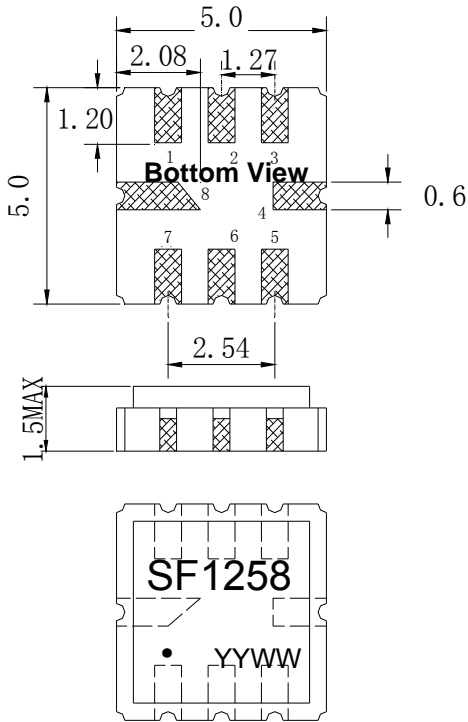
- Low-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable passband 5.5 MHz



Features

- Ceramic Package for **Surface Mounted Technology (SMT)**
- **RoHS** compatible
- Package size 5.00x5.00x1.50mm³
- Package Code QCC8C
- **Electrostatic Sensitive Device(ESD)**

Package Dimensions (Unit: mm)



Pin Configuration

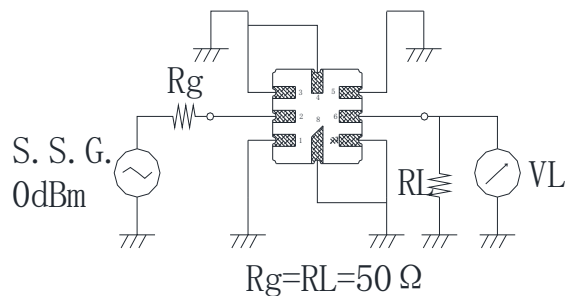
| Pin No. | Description |
|-------------|-------------|
| 2 | Input |
| 6 | Output |
| 1,3,4,5,7,8 | Ground |

Marking Description

| | |
|-------------|-----------------------|
| S | Trademark |
| F | SAW Filter |
| 1258 | Part Number |
| ● | Pin 1 |
| YYWW | Year Code & Week Code |

*Fig: If the products produced in 06th week of 2012, The year code & week code is 1206.

Test Circuit(Bottom View)



Performance**Maximum Rating**

| Item | | Value | Unit |
|-----------------------|------------------|------------|------|
| DC Voltage | V _{DC} | 3 | V |
| Operation Temperature | T | -40 ~ +85 | °C |
| Storage Temperature | T _{stg} | -55 ~ +125 | °C |
| RF Power Dissipation | P | 10 | dBm |

Electronic Characteristics

Test Temperature: 25°C ± 2°C

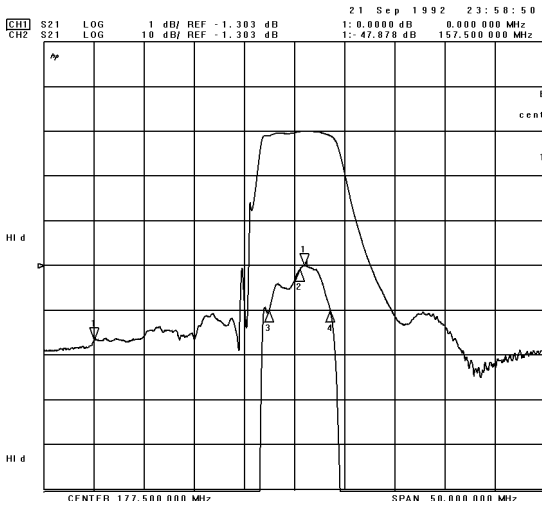
Terminating source impedance: 50Ω

Terminating load impedance: 50Ω

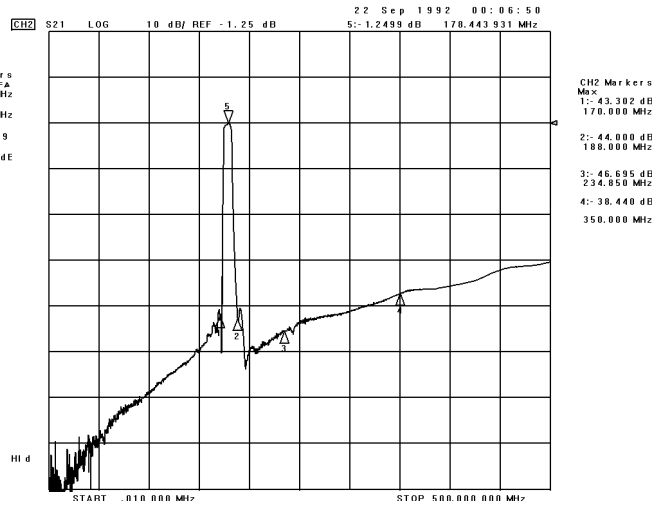
| Item | | Minimum | Typical | Maximum | Unit |
|---|-------------------|---------|---------|---------|------|
| Center Frequency | f _c | | 177.5 | | MHz |
| Insertion Loss(min) | IL | | 1.3 | 2.0 | dB |
| Amplitude Ripple (p-p) 174.75-180.25 MHz | Δα | | 0.8 | 1.0 | dB |
| 1 dB Bandwidth | BW _{1dB} | 5.5 | 6.1 | | MHz |
| Group Delay Ripple 174.75-180.25 MHz | GDR | | 100.0 | 200.0 | ns |
| Phase Linearity 174.75-180.25 MHz | | | 20.0 | 25.0 | deg |
| Absolute Attenuation | α | | | | |
| DC-157.50 MHz | | 45.0 | 48.0 | | dB |
| 157.50-168.50 MHz | | 40.0 | 45.0 | | dB |
| 168.50-171.50MHz | | 20.0 | 40.0 | | dB |
| 183.50-191.50 MHz | | 19.0 | 24.0 | | dB |
| 191.50-197.50 MHz | | 40.0 | 42.0 | | dB |
| 197.50-230.00 MHz | | 45.0 | 48.0 | | dB |
| Input VSWR 174.75-180.25 MHz | | | 1.7:1 | 2.0:1 | / |
| Output VSWR 174.75-180.25 MHz | | | 1.7:1 | 2.0:1 | / |

Frequency Characteristics

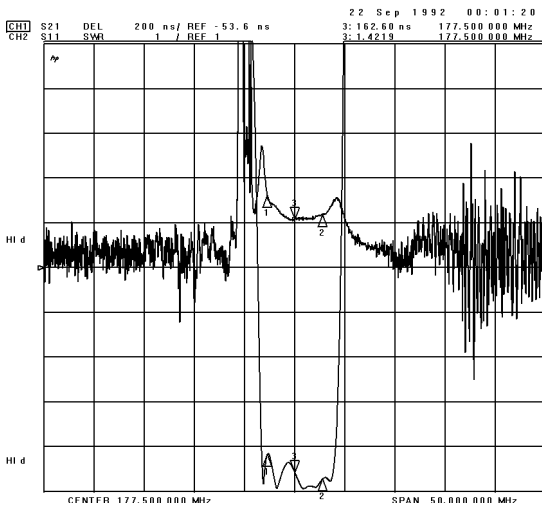
Frequency Response



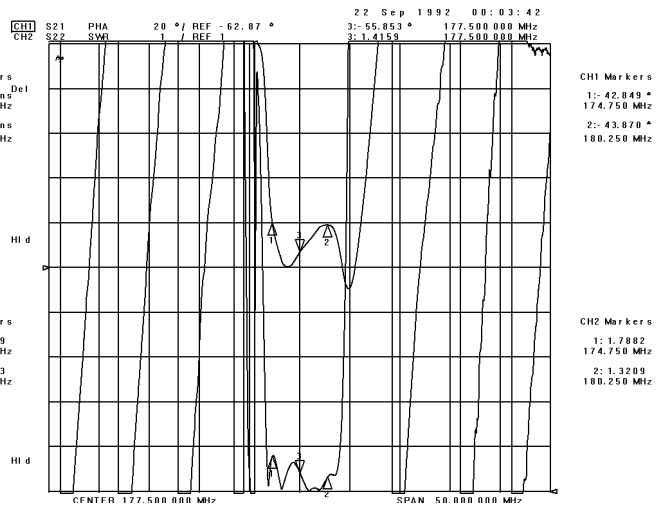
Frequency Response (wideband)



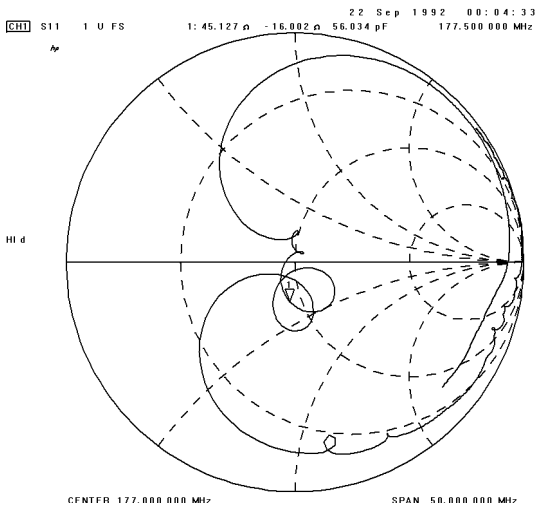
Delay Ripple & S11 VSWR



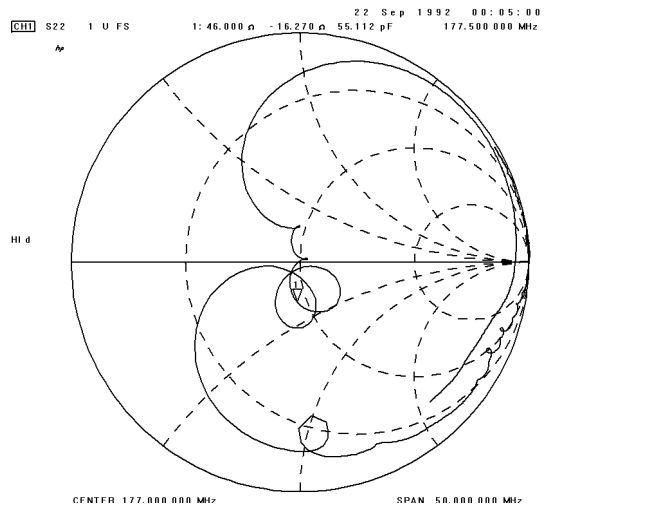
Phase Linearity & S22 VSWR



S11 Smith Chart

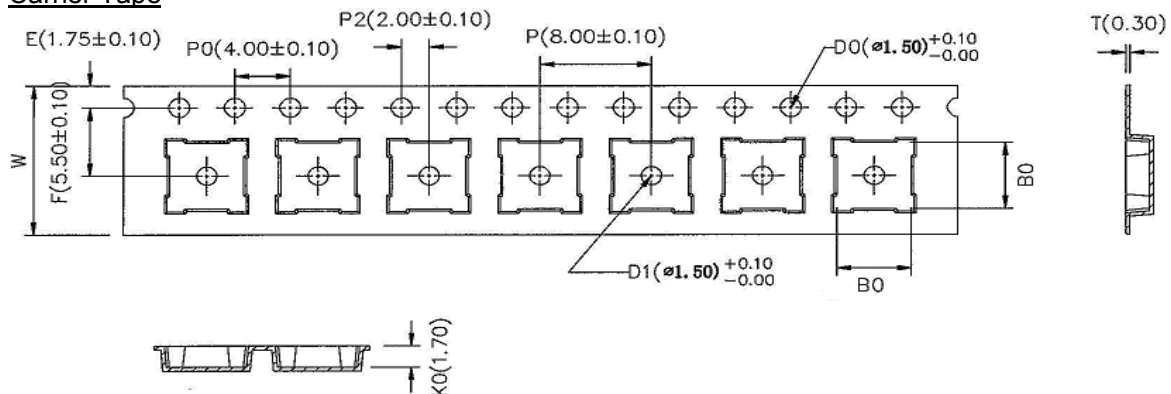


S22 Smith Chart



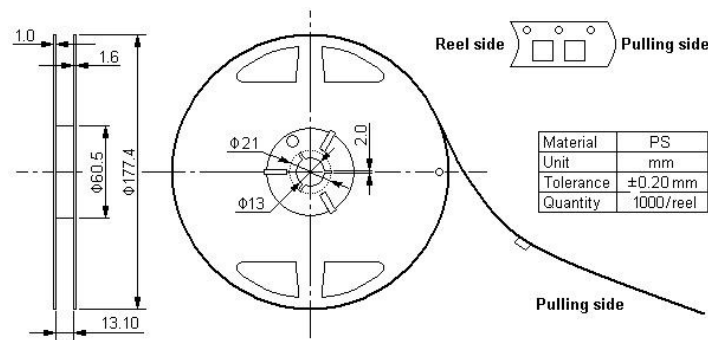
Packing Information

Carrier Tape



* B0: 5.35 for QCC8C; 4.15 for DCC6/QCC8B; 3.35 for DCC6C/QCC8D

Reel Dimensions



| | |
|-----------|-----------|
| Material | PS |
| Unit | mm |
| Tolerance | ±0.20 mm |
| Quantity | 1000/reel |

Outer Packing

| Type | Quantity | Dimension | Description | Weight |
|--------------|----------|-------------|---|--------|
| Internal box | 1000 | 190×188×42 | carton box | 0.18 |
| External box | 10000 | 235×205×210 | 2 reel / internal box 5 boxes / external box | |

Unit: mm

Unit: kg

Notes

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.